

**DECLARATION FOR UNITED STATES PATENT APPLICATION,  
POWER OF ATTORNEY, DESIGNATION OF CORRESPONDENCE ADDRESS**

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and that I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

**COLLECTIVE SUBSTRATE, SEMICONDUCTOR ELEMENT MOUNT, SEMICONDUCTOR DEVICE,  
IMAGING DEVICE, LIGHT EMITTING DIODE COMPONENT AND LIGHT EMITTING DIODE**

\_\_\_\_\_ the specification of which

☐ is attached hereto.

☐ was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_  
and was amended on \_\_\_\_\_ (if applicable).

☒ was filed under the Patent Cooperation Treaty on July 21, 2005  
Serial No. PCT/JP2005/013402, the United States of America being designated.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose to the Patent and Trademark Office information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Country	Number	Date Filed	Priority Claimed	Yes	No
Japan	2004-231085	August 6, 2004	✓		
Japan	2005-047481	February 23, 2005	✓		

I hereby appoint the following attorneys to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith: Steven M. Rabin (Reg. No. 29,102), Robert H. Berdo, Jr. (Reg. No. 38,075), Phillip G. Avruch (Reg. No. 46, 076) and Allen Wood (Reg. No. 28,134).

Address all correspondence to:

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Patent Trademark Office

The undersigned hereby authorizes the U.S. attorneys named herein to accept and follow instructions from the undersigned's assignee, if any, and/or, if the undersigned is not a resident of the United States, the undersigned's domestic attorney, patent attorney, patent agent, or patent representative as to any action to be taken in the Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and the undersigned. In the event of a change in the person(s) from whom instructions may be taken, the U.S. attorneys named herein will be so notified by the undersigned.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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